## DEPARTMENT OF ELECTRICAL ENGINEERING I. I. T. KANPUR

## **Printed Circuit Board Fabrication Facility**

-7628

	Job Order for Making PCB	Tel. No.
	8	
h Ondon No		Doto

Job Order No. :		Date		
Name of Indentor: _		Tel. No	Tel. No	
Name of the Depart	ment :			
Designation /Roll N	0. :			
Nature of Project: B	3.Tech/M.Tech /Ph.D./Rese	rch/Lab. Development/Cou	ırse.	
Project No. if any:				
Description of Circu	ıit:			
Size of PCB/Mask:		No. of PCB/Mask:		
Job Requirements	(Tick the items needed):			
Photographic	: Camera /Contact Print	Photo plotting (GBR	files)	
	CNC Drilling	CNC Milling/Chemi	cal Etch.	
Microwave PCB	: Without Gold plating	Copper Platin	ıg 🗀	
Solder Masking	: Top Layer	Bottom Layer		
Legend Printing	: Top Layer	Bottom Layer		
Copper Clad Sheet:	S.S.Paper Phenolic	D.S.Epoxy Non -PTH		
	S.S.Epoxy	D.S.Epoxy PTH		
PCB Design File Na	ame:	Multi-	layer PCBs:	
PCB File	:	Four la	yers	
DDB File	:	Six lay	ers	
Laser Printout File	:	Eight la	ayers 🔲	
Signature of Indento	Dr	Signature of the Proj. Co Investigator/Course Co- Head of the department.	ordinator/	
Incharge PCB Facil	ity. Faculty Co- ordi		ACES	

PCB Fabrication Facility

(For external & Chargeable Job)

Signature of the Receiver.				
Date :				
For Sponsored Project /Research/Lab Deve	elopment/Course.			
Total Cost –Rs				
The amount of Rs.				
may be transferred from Project No./Departm	ent			
	to Project No. IITK/EE/2022556.			
Head of the Department	Project Investigator			
This is to declare that the PCB being ordered will $\!\!\!/$ will not be used for a Sponsored Project.				
Signature of Indentor (Faculty Supervisor for	Student Indentors)			

Checked and received the above PCB from the Printed Circuits Board Fabrication Facility.